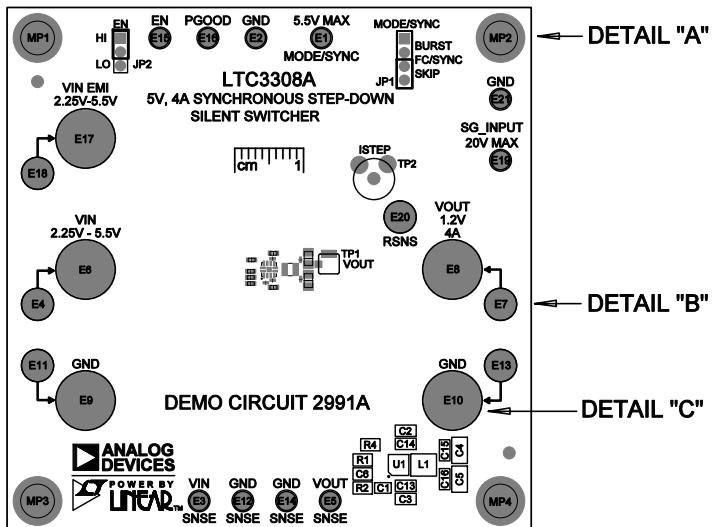


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	02	PRODUCTION	MM	09-19-19

NOTES: UNLESS OTHERWISE SPECIFIED

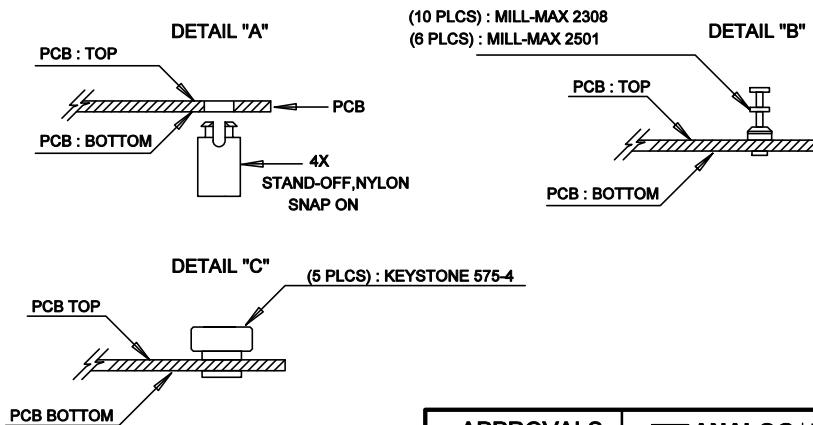


DETAIL "A"

DETAIL "B"

DETAIL "C"

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AS SHOWN BELOW:
8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.



APPROVALS

PCB DES NC

APP ENG MM



TITLE: TOP ASSEMBLY DRAWING
5V, 4A SYNCHRONOUS STEP-DOWN
SILENT SWITCHER

SIZE IC NO. LTC3308
N/A N/A DEMO CIRCUIT 2991A REV.
02

SCALE = NONE

SHT 1 OF 1